

ICPT 2026

October 19-22, 2026

Science and Technology Convention Center,
Seoul, South Korea

October 20 (Tue.), 2026

[Oral 03] CMP for Advanced Packaging/3D Integration (I)

14:20-15:20

International Conference Hall (B1F)

● Session Chair: Bradley Wood (SPS International, USA)

14:20-14:40 [Panel-Level CMP Integration for Cu RDLs in Fine-Pitch Fan-Out Panel-Level Packaging](#)
[Oral 03-1]

Eungchul Kim, Suhyeon Jeon (Samsung Electronics Co., Ltd., Korea), Yuya Otsuka, Takehiro Yamazaki, Shinya Watanabe (DSRJ, Japan), Yongrae Kim, Dongjoon Oh, Juil Choi, and Minwoo Rhee (Samsung Electronics Co., Ltd., Korea)

14:40-15:00 [Process Optimization of Bulk Si Thinning for Advanced Logic Architectures](#)
[Oral 03-2]

Lea Di Donato, Bart Kenens, and Kevin Vandersmissen (imec, Belgium)

15:00-15:20 [Sub-10nm Cu/SiO₂ Dishing Control for 3D Heterogeneous Integration](#)
★[Oral 03-3]

Jinhyoung Lee, Junmin Ahn, and Taesung Kim (Sungkyunkwan Univ., Korea)